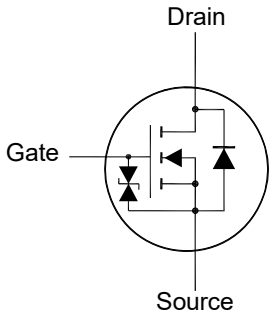
MKA06N090LZK

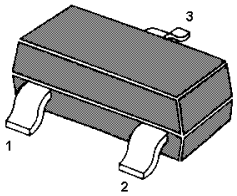
N-Channel Enhancement Mode MOSFET

Features

- Surface-mounted package
- Built-in G-S Protection Diode
- Typical ESD Protection HBM Class 2

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000





1. Gate 2. Source 3. Drain
SOT-23 Plastic Package

Applications

- Portable appliances
- Battery management

Absolute Maximum Ratings(at T_a = 25℃ unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	V
Drain Current		I_D	3	A
Peak Drain Current, Pulsed [1]		I_{DM}	12	A
Total Power Dissipation [2]	t ≤ 10 s Steady State	P_{tot}	1.25 0.54	W
Operating Junction and Storage Temperature Range		T_j, T_{stg}	- 55 to + 150	℃

Thermal Characteristics

Parameter		Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient [2]	t ≤ 10 s Steady State	$R_{\theta JA}$	100 232	℃/W

[1] Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ = 150°C.

[2] Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

Dated: 06/03/2024 Rev:01

Characteristics at T_a = 25℃ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at I_D = 250 µA	BV_{DSS}	60	-	-	V
Drain-Source Leakage Current at V_{DS} = 48 V	I_{DSS}	-	-	1	µA
Gate Leakage Current at V_{GS} = ± 16 V	I_{GSS}	-	-	± 10	µA
Gate-Source Threshold Voltage at V_{DS} = V_{GS}, I_D = 250 µA	$V_{GS(th)}$	1.2	-	2.5	V
Drain-Source On-State Resistance at V_{GS} = 10 V, I_D = 3 A at V_{GS} = 4.5 V, I_D = 1 A	$R_{DS(on)}$	- -	- -	75 90	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at V_{DS} = 5 V, I_D = 2 A	g_{FS}	-	4.2	-	S
Gate Resistance at V_{DS} = 0 V, V_{GS} = 0 V, f = 1 MHz	R_g	-	1.3	-	Ω
Input Capacitance at V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz	C_{iss}	-	445	-	pF
Output Capacitance at V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz	C_{oss}	-	22	-	pF
Reverse Transfer Capacitance at V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz	C_{rss}	-	18	-	pF
Gate Charge Total at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A at V_{DS} = 30 V, V_{GS} = 4.5 V, I_D = 2 A	Q_g	- -	8.6 4	- -	nC
Gate to Source Charge at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A	Q_{gs}	-	1.8	-	nC
Gate to Drain Charge at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A	Q_{gd}	-	1.2	-	nC
Turn-On Delay Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A, R_g = 4.7 Ω	$t_{d(on)}$	-	7	-	ns
Turn-On Rise Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A, R_g = 4.7 Ω	t_r	-	2	-	ns
Turn-Off Delay Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A, R_g = 4.7 Ω	$t_{d(off)}$	-	6	-	ns
Turn-Off Fall Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 2 A, R_g = 4.7 Ω	t_f	-	5	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at I_S = 1 A	V_{SD}	-	-	1.2	V
Body Diodes Continuous Current	I_S	-	-	3	A
Body Diode Reverse Recovery Time at I_S = 2 A, di/dt = 100 A / µs	t_{rr}	-	8	-	ns
Body Diode Reverse Recovery Charge at I_S = 2 A, di/dt = 100 A / µs	Q_{rr}	-	4	-	nC

Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

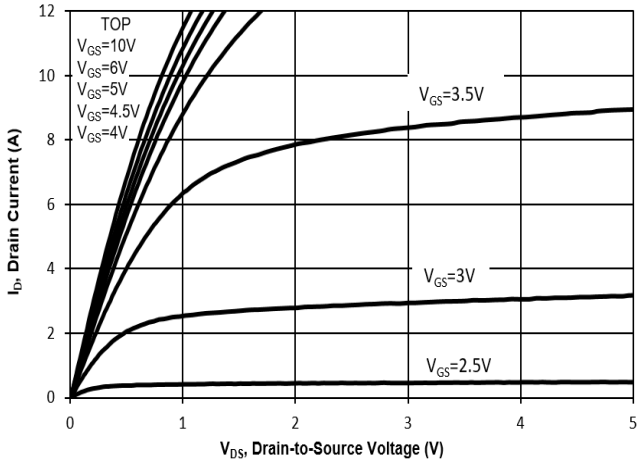


Fig. 2 Typical Transfer Characteristics

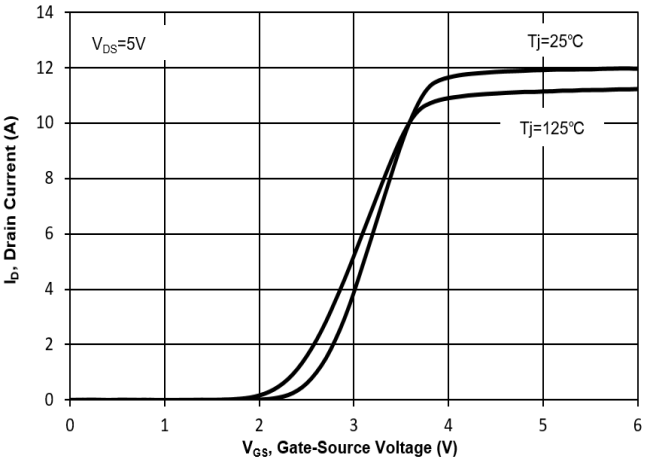


Fig. 3 On-Resistance vs. Drain Current

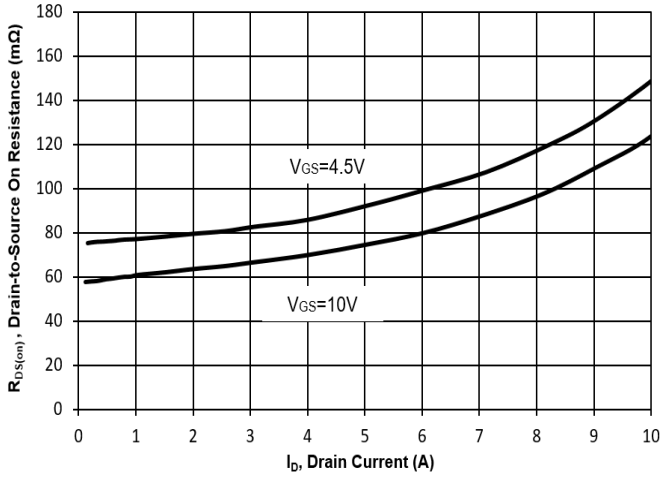


Fig. 4 On-Resistance vs. Gate-Source Voltage

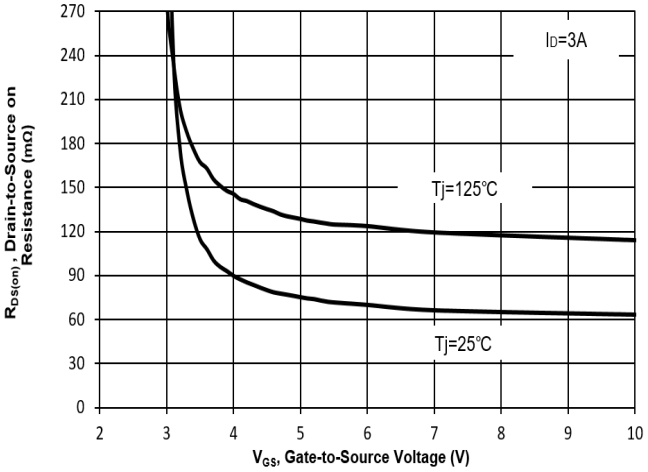


Fig. 5 On-Resistance vs.T_j

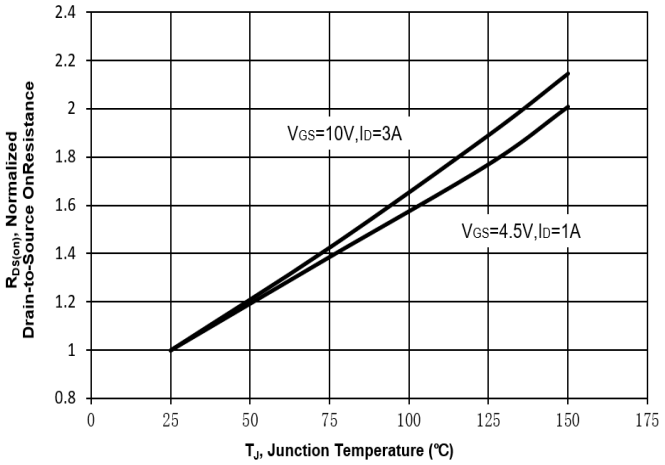
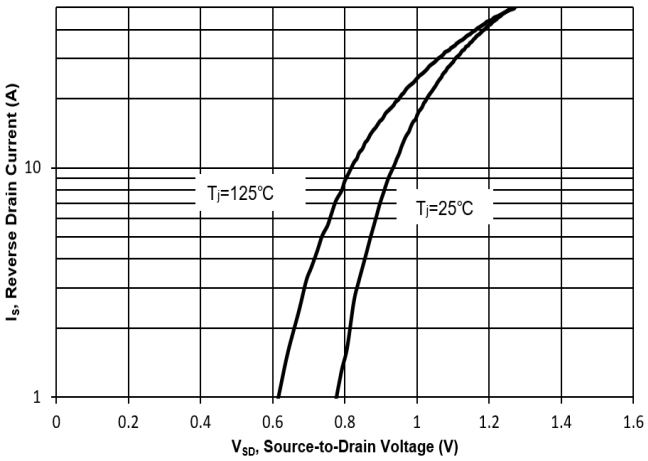


Fig. 6 Typical Body-Diode Forward Characteristics



Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

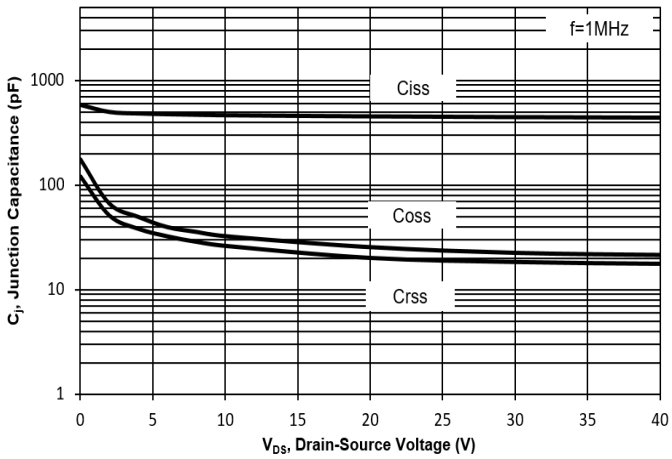


Fig. 8 Drain-Source Leakage Current vs. T_j

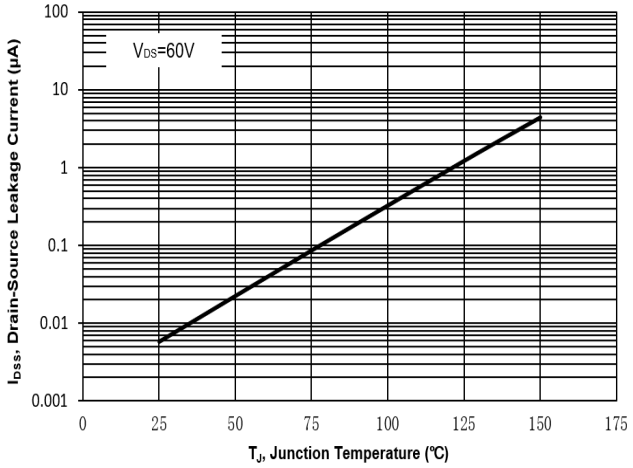


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

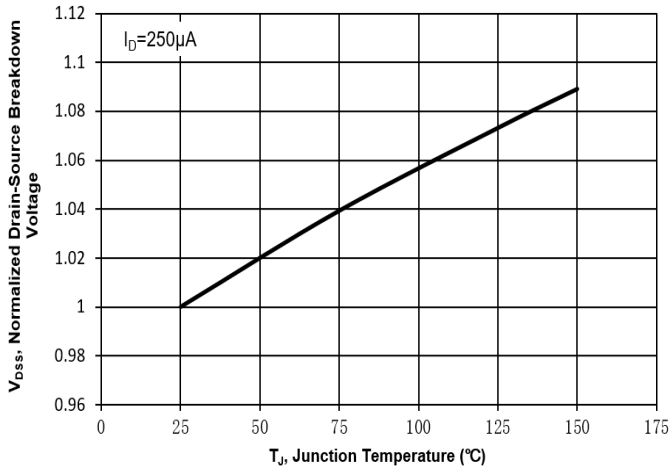


Fig. 10 Gate Threshold Variation vs. T_j

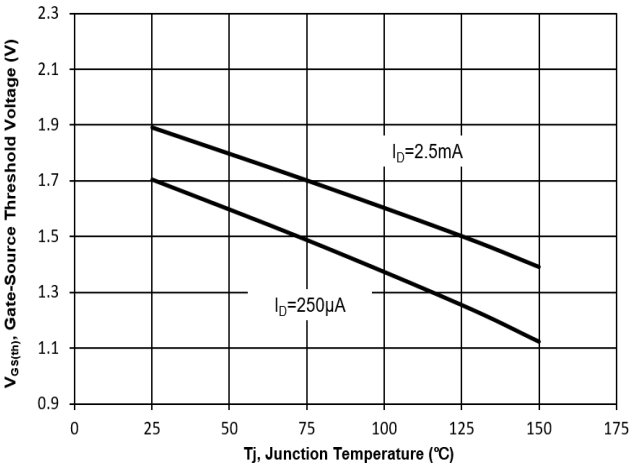
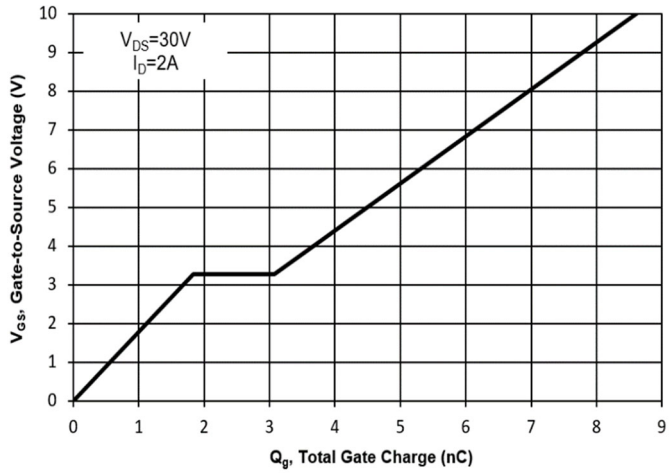


Fig. 11 Gate Charge



Test Circuits

Fig.1-1 Switching times test circuit

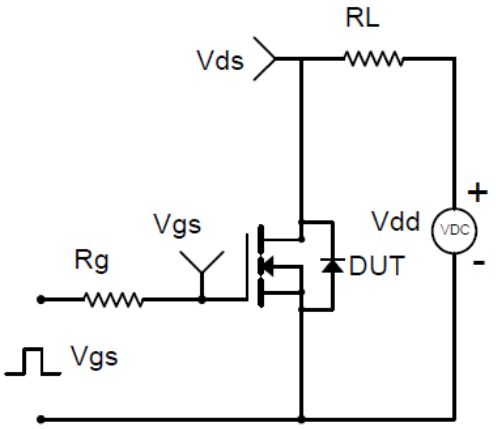


Fig.1-2 Switching Waveform

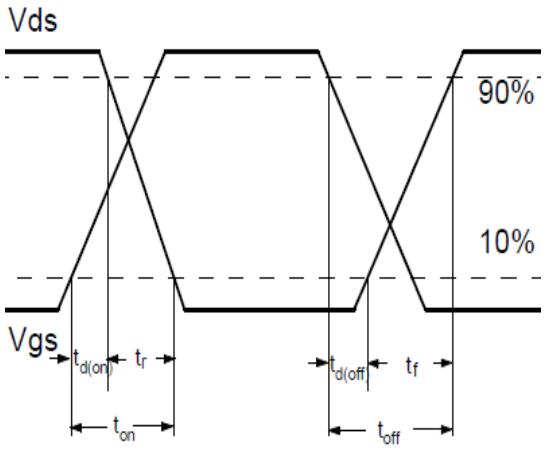


Fig.2-1 Gate charge test circuit

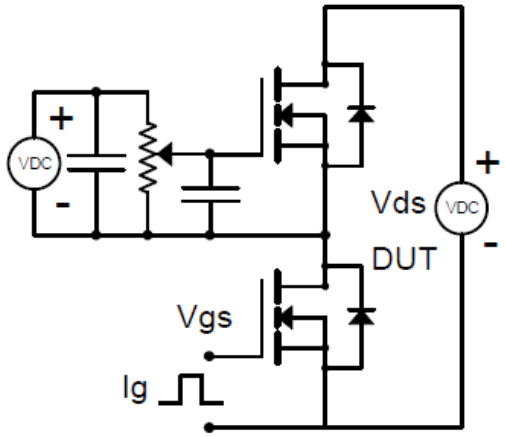
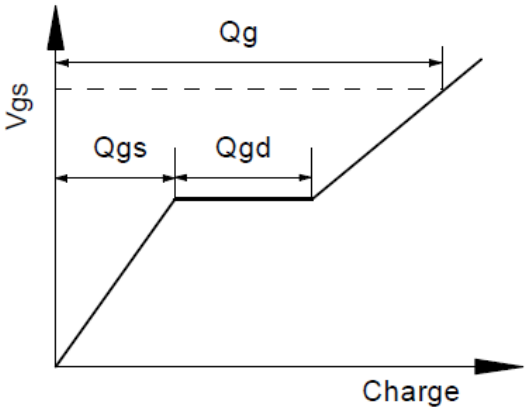
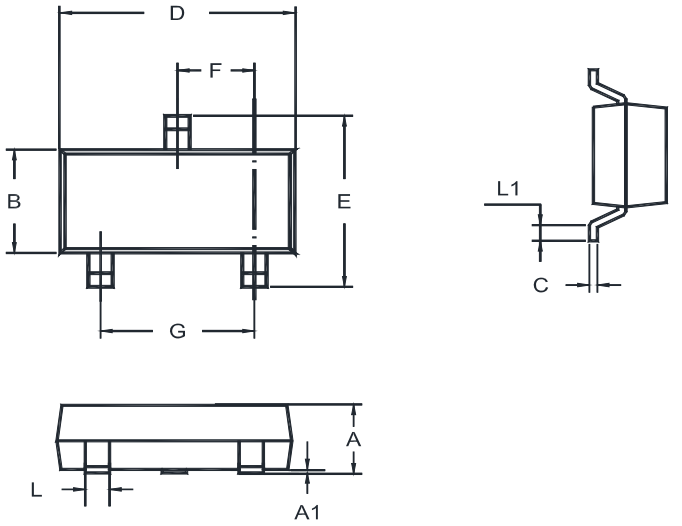


Fig.2-2 Gate charge waveform

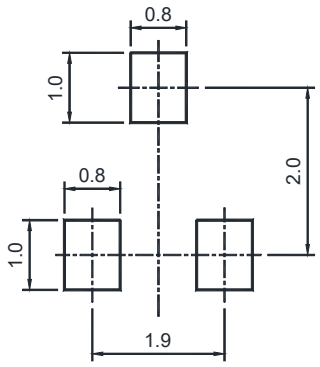


Package Outline (Dimensions in mm) SOT-23



Unit	A	A1	B	C	D	E	F	G	L	L1
mm	1.20 0.89	0.100 0.013	1.40 1.20	0.19 0.08	3.04 2.80	2.6 2.2	1.02 0.89	2.04 1.78	0.51 0.37	0.2 MIN

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" QH1 " = Part No.
" YM " = Date Code Marking
" Y " = Year
" M " = Month
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